

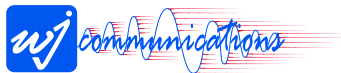


**SOIC8 Material Constituents for Lead Free and Green Packages
applicable to AG606, AHxx and ECPxxxG-G series**

Package Element	Material Type	CAS Number	Weight (mg)	ppm
SOIC-8 Leadframe Bulk	Copper	7440-50-8	35.80	468,571
SOIC-8 Leadframe Bulk	Iron	7439-89-6	0.89	11,649
SOIC-8 Leadframe Bulk	Phosphorus	7723-14-0	0.22	2,879
SOIC-8 Leadframe Bulk	Zinc	7440-66-6	0.05	589
SOIC-8 Leadframe Bulk	Nickel	7440-02-0	0.15	1,963
SOIC8 NiPdAu Plating	Nickel		0.70	9,162
SOIC8 NiPdAu Plating	Palladium		0.10	1,309
SOIC8 NiPdAu Plating	Gold	7440-22-4	0.01	65
Die Attach Epoxy*	Silver	7440-22-4	0.01	131
Die Attach Epoxy*	Epoxy Resin		0.01	65
Die Attach Epoxy*	Aromatic Amine		0.00	7
Wirebond And Die Metallization	Gold	7440-57-5	0.07	877
SOIC-8 Package Molding Compound	Epoxide Resins		2.40	31,413
SOIC-8 Package Molding Compound	Silica	7631-86-9	34.00	445,012
SOIC-8 Package Molding Compound	Epoxy, Cresol Novolac		1.60	20,942
SOIC-8 Package Molding Compound	Carbon	7440-44-0	0.08	1,047
Active Semiconductor Die*	Arsenic	7440-38-2	0.15	1,963
Active Semiconductor Die*	Gallium	7440-55-3	0.18	2,356
		TOTALS	76.40	1,000,000

* individual amounts vary slightly based on die size

If you have any questions, please contact Tad Custer, Product Line Manager,
408-577-6370 or Tad.Custer@wj.com



401 River Oaks Parkway
San Jose, CA 95134

SIZE

DWG. NO.

454699

SCALE

REV.

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SHEET

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